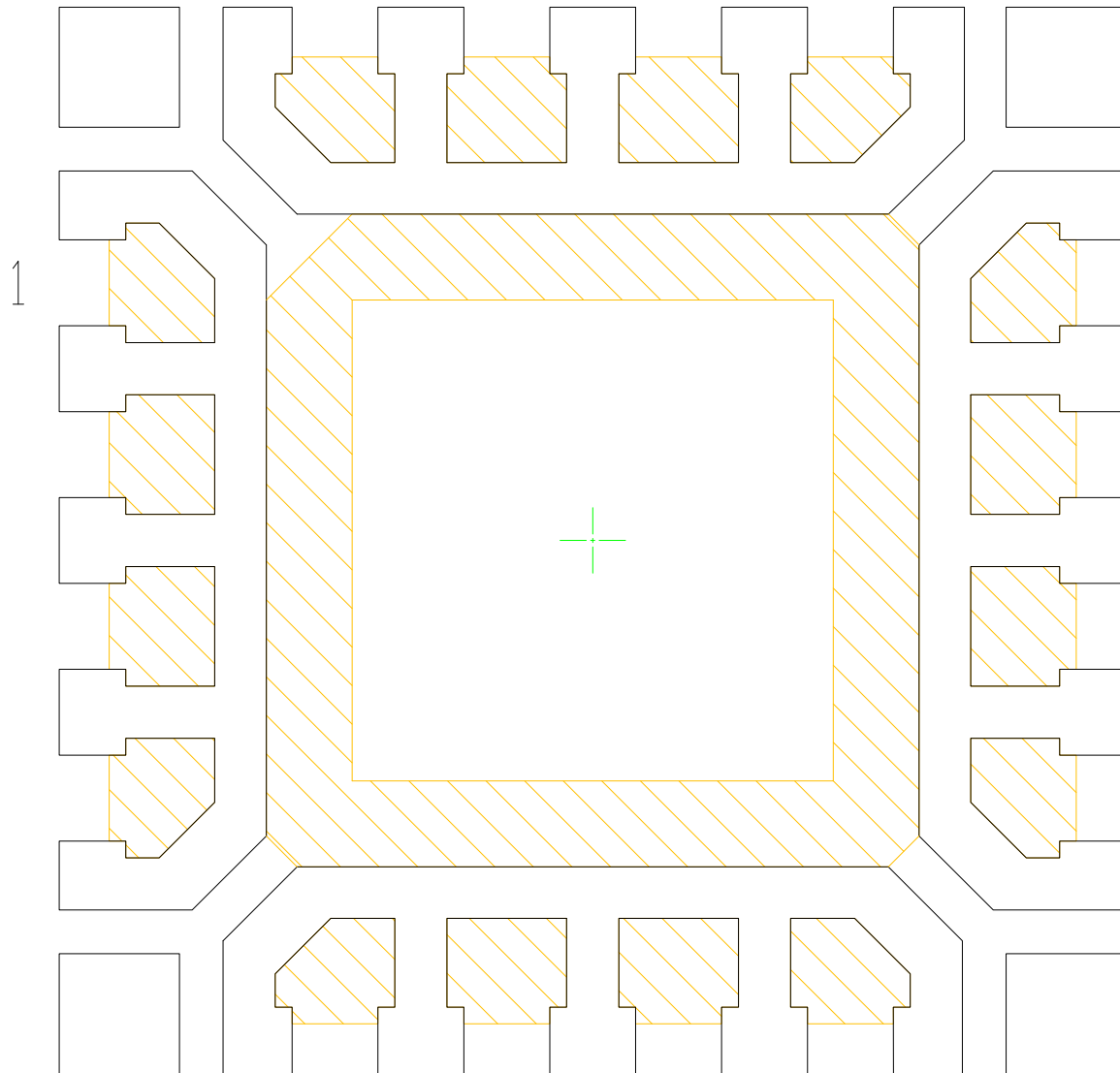


REVISIONS		
REV	DESCRIPTION	DATE
C	INCREASED DAP SIZE, REDUCED GROUND RING WIDTH	07/24/17



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	PROMEX INDUSTRIES INC. www.promex-ind.com
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 1.90 x 1.90 mm	
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 1.65 x 1.65 mm	TITLE QFN 16L 3x3 mm 0.50 PITCH BOND SHELL
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	LEADFRAME P/N: 235-00050
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	REV 00
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE
		FILE NAME 16L-QFN-3X3-50P-BD.DWG
		SHEET 1 OF 1